



Polyphenylene sulfide

Fortron 6165A6 is an easier flow version of Fortron 6165A4. It offers similar characteristics to the 6165A4. Applications include electronic components (i.e. lamps housings and sockets) and mechanical components (i.e. pumps and pistons).

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Resin Identification	PPS-(GF+MD)6 5		ISO 1043	
Part Marking Code	>PPS-(GF+MD)6	5<	ISO 11469	
Rheological properties				
Moulding shrinkage, parallel Moulding shrinkage, normal	0.2 0.5		ISO 294-4, 2577 ISO 294-4, 2577	
Typical mechanical properties				
Tensile modulus	19500	MPa	ISO 527-1/-2	
Tensile stress at break, 5mm/min	135	MPa	ISO 527-1/-2	
Tensile strain at break, 5mm/min	1.2	%	ISO 527-1/-2	
Flexural modulus	19000	MPa	ISO 178	
Flexural strength		MPa	ISO 178	
Compressive modulus	18500		ISO 604	
Compressive strength		MPa	ISO 604	
Charpy impact strength, 23°C		kJ/m²	ISO 179/1eU	
Charpy impact strength, -30°C		kJ/m²	ISO 179/1eU	
Charpy notched impact strength, 23°C		kJ/m²	ISO 179/1eA	
Charpy notched impact strength, -30°C		kJ/m²	ISO 179/1eA	
Izod notched impact strength, 23°C		kJ/m²	ISO 180/1A	
Izod notched impact strength, -30°C		kJ/m²	ISO 180/1A	
Izod impact strength, 23°C		kJ/m²	ISO 180/1U	
Izod impact strength, -30°C		kJ/m²	ISO 180/1U	
Hardness, Rockwell, M-scale	100		ISO 2039-2	
Poisson's ratio	0.33 ^[C]			
[C]: Calculated				
Thermal properties				
Melting temperature, 10°C/min	280	°C	ISO 11357-1/-3	
Glass transition temperature, 10°C/min	90	°C	ISO 11357-1/-3	
Temperature of deflection under load, 1.8 MPa	270	°C	ISO 75-1/-2	
Temperature of deflection under load, 8 MPa	215	°C	ISO 75-1/-2	
Coefficient of linear thermal expansion	19	E-6/K	ISO 11359-1/-2	
(CLTE), parallel				
Coefficient of linear thermal expansion (CLTE), normal	24	E-6/K	ISO 11359-1/-2	
Thermal conductivity, flow	0.7	W/(m K)	ISO 22007-2	
Thermal conductivity, crossflow		W/(m K)	ISO 22007-2	
Thermal conductivity, through plane		W/(m K)	ISO 22007-2	
Specific heat capacity of melt	1600	J/(kg K)	ISO 22007-4	

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Flammability

Burning Behav. at 1.5mm nom. thickn.	V-0 class	IEC 60695-11-10
Thickness tested	1.5 mm	IEC 60695-11-10
Burning Behav. at thickness h	V-0 class	IEC 60695-11-10
Thickness tested	0.75 mm	IEC 60695-11-10

Electrical properties

Relative permittivity, 1MHz	5.6	IEC 62631-2-1
Dissipation factor, 1MHz	20 E-4	IEC 62631-2-1
Volume resistivity	>1E13 Ohm.m	IEC 62631-3-1
Surface resistivity	>1E15 Ohm	IEC 62631-3-2
Electric strength	25 kV/mm	IEC 60243-1
Arc Resistance	182 s	UL 746B

Physical/Other properties

Water absorption, 2mm	0.02 %	Sim. to ISO 62
Water absorption, Immersion 24h	0.03 %	Sim. to ISO 62
Density	2000 kg/m ³	ISO 1183

Injection

Drying Recommended	yes	
Drying Temperature	130	°C
Drying Time, Dehumidified Dryer	2 - 4	h
Processing Moisture Content	≤0.02	%
Melt Temperature Optimum	330	°C
Min. melt temperature	310	°C
Max. melt temperature	340	°C
Screw tangential speed	0.2 - 0.3	m/s
Mold Temperature Optimum	150	°C
Min. mould temperature	140	°C
Max. mould temperature	160	°C
Hold pressure range	30 - 70	MPa
Back pressure	3	MPa
Ejection temperature	219	°C

Characteristics

Processing Injection Moulding

Delivery form Pellets

Additives Release agent

Special characteristics Flame retardant, Light stabilised or stable to light, Heat stabilised or stable to heat,

High Flow, Chemical resistant

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Additional information

Injection molding

Preprocessing

Predrying in a dehumidified air dryer at 130 - 140 degC/3-4 hours is recommended.

Processing

On injection molding machines with 15-25 D long three-section screws, as are usual in the trade, the FORTRON is processable. A shut-off nozzle is preferred to a free-flow nozzle.

Melt temperature 320-340 degC Mold wall temperature at least 140 degC

A medium injection rate is normally preferred. All mold cavities must be effectively vented.

Postprocessing

Tool temperature of at least 135 degC is recommended for parts to achieve maximum crystallizable potential.

Processing Notes

Pre-Drying

FORTRON should in principle be predried. Because of the necessary low maximum residual moisture content the use of dry air dryers is recommended. The dew point should be =< - 30° C. The time between drying and processing should be as short as possible.

Storage

For subsequent storage the material should be stored dry in the dryer until processed (\leq 60 h).

Automotive

OEM STANDARD ADDITIONAL INFORMATION

 Continental
 TST N 055 58.01

 Ford
 WSF-M4D803-A2

Mercedes-Benz DBL5404 Black

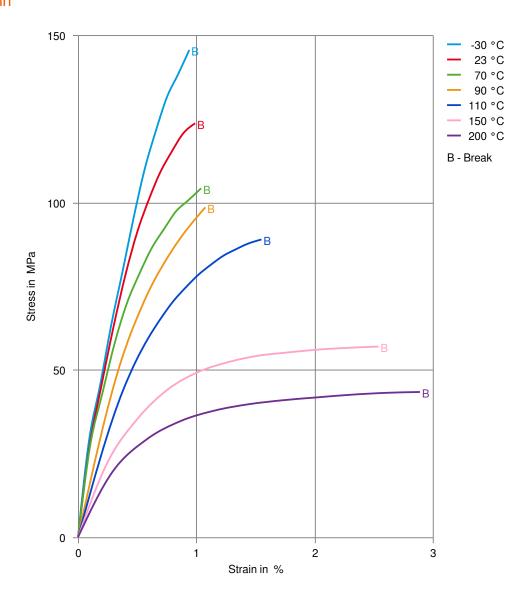
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Stress-strain



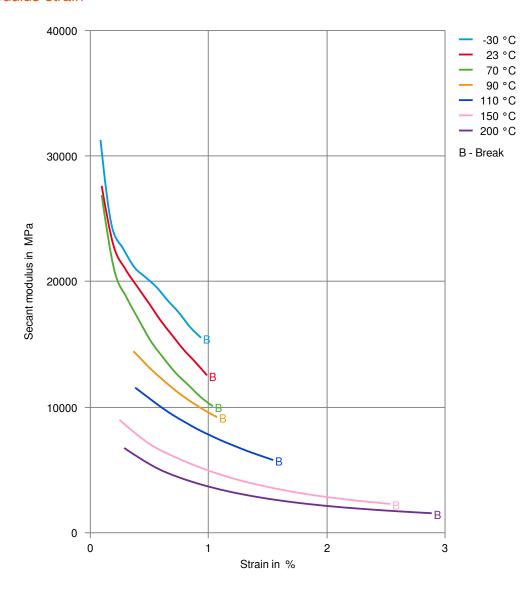
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Polyphenylene sulfide

Secant modulus-strain



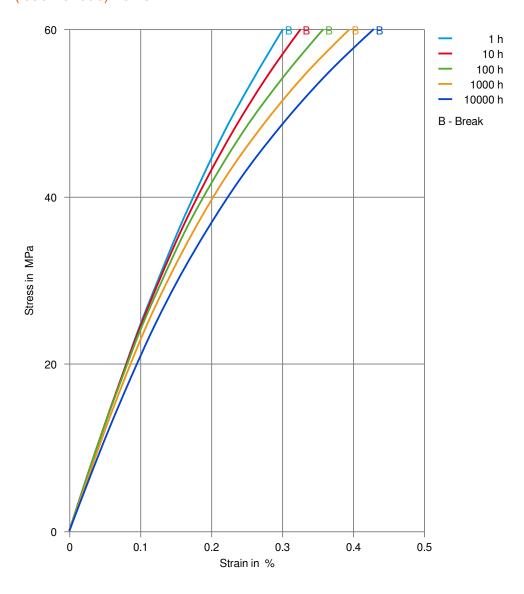
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Polyphenylene sulfide

Stress-strain (isochronous) 23°C



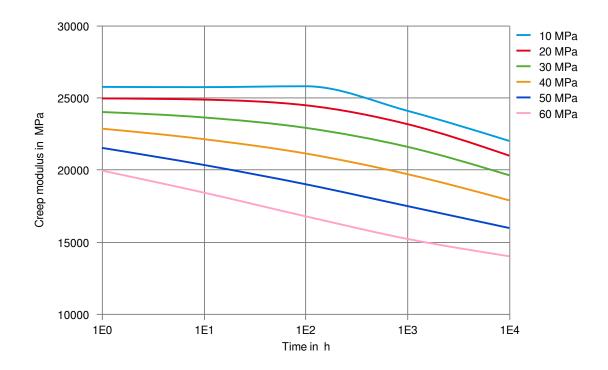
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Polyphenylene sulfide

Creep modulus-time 23°C



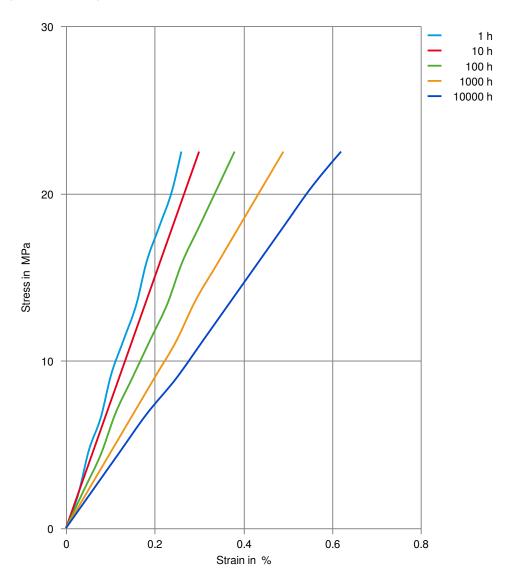
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Polyphenylene sulfide

Stress-strain (isochronous) 120°C



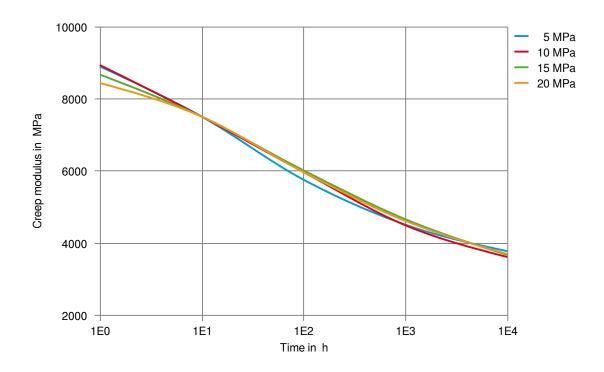
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Polyphenylene sulfide

Creep modulus-time 120°C



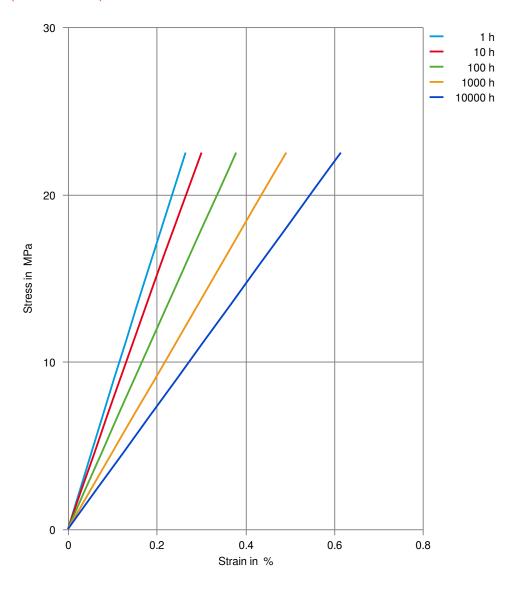
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Polyphenylene sulfide

Stress-strain (isochronous) 150°C



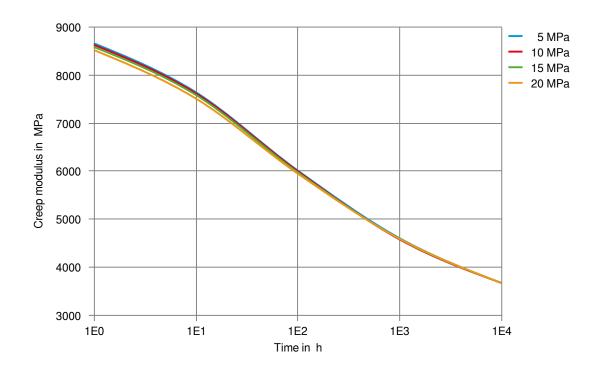
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Polyphenylene sulfide

Creep modulus-time 150°C



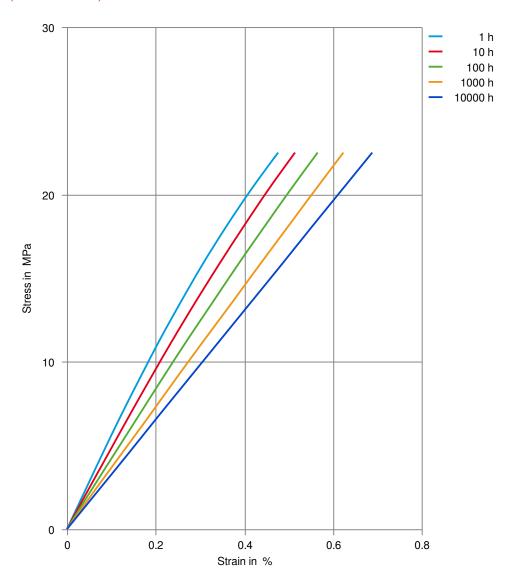
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Polyphenylene sulfide

Stress-strain (isochronous) 200°C



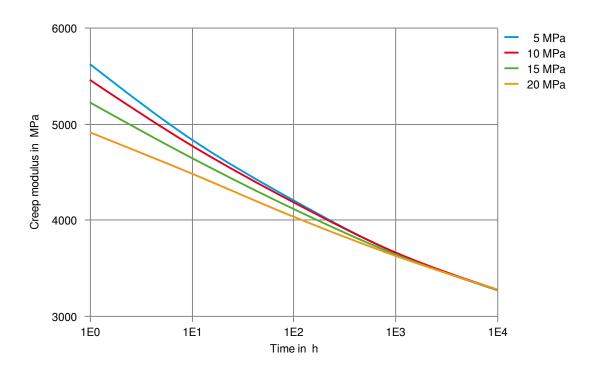
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Creep modulus-time 200°C



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Revised: 2024-09-09 Source: Celanese Materials Database

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